

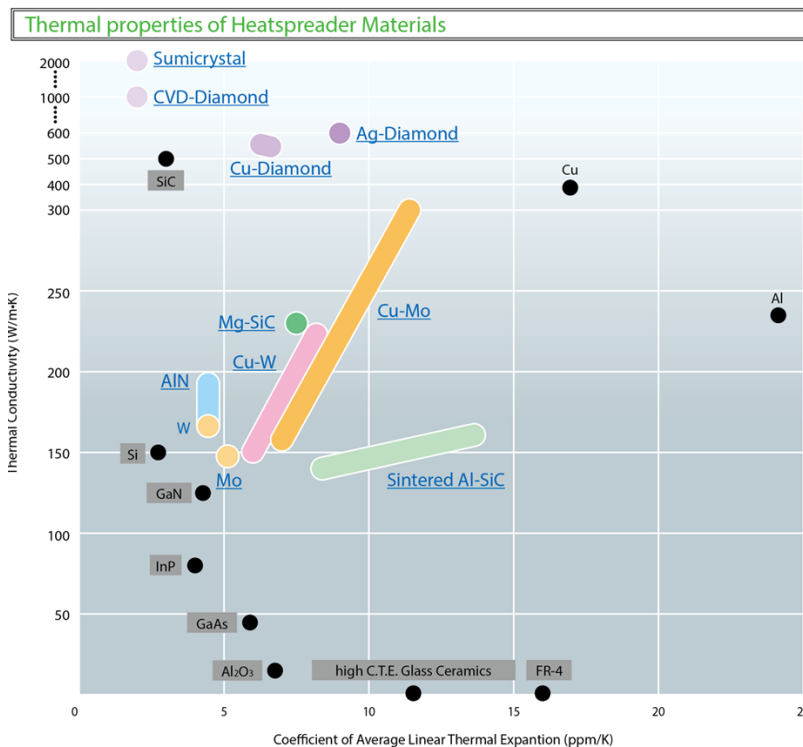
Effective Advanced Heat Spreading Thermal Solutions For GaN Devices

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Sumitomo Electric USA (Thermal Solutions Group), and sister division ALMT, offers advanced thermal management material options to help with increasing GaN, GaAs and WBG devices' thermal challenges.

Demands are constantly pushing GaN devices for higher power, increased performance with increased life, smaller footprints are driving intense areas of heat. Finding a suitable material to meet those heat spreading demands reliably can be a task.

This presentation will focus on our Silver Diamond material well suited for GaN devices, but also cover other effective thermal solutions with thermal conductivity up to 2,000 W/mK. Silver Diamond offers excellent thermal performance, reliable and robust.



Keywords
Silver Diamond
Copper Diamond
Single Crystal Diamond
CVD Diamond
Tungsten Copper (WCu, CuW)
Molybdenum Copper (MoCu, CuMo)
CPC
CMC
Aluminum Nitride (AlN)
AlSiC